501954217 06/13/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Takanori HIRAMOTO	04/26/2012
Toshio HINO	04/26/2012
Tsuyoshi SAKATA	04/26/2012
Yutaka MIZUNO	04/26/2012
Katsuya OGATA	04/26/2012

RECEIVING PARTY DATA

Name: FUJITSU SEMICONDUCTOR LIMITED	
Street Address: 2-10-23 Shin-Yokohama, Kohoku-ku	
City:	Yokohama-shi, Kanagawa
State/Country:	JAPAN
Postal Code: 222-0033	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13494145

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	111599
NAME OF SUBMITTER:	Crystal Boyer

PATENT REEL: 028368 FRAME: 0955 DP \$40.00 13494145

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Total Attachments: 5

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PATENT REEL: 028368 FRAME: 0956

unde	I CONSIDERATION of the sum of reigned inventor(s) (hereinafter, " int Name(s) & Address(es) of ASS	'ASSIGNOR") by	and of other goo	d and valuable consideration paid to the
	FUJITSU SEMICONDUCTO			
	2-10-23 Shin-Yokohama, Ko	ohoku-ku, Yokoh	ama-shi, Kana	gawa 222-0033 Japan
assig	einafter, "ASSIGNEE"), the receip ins and transfers to ASSIGNEE to of Invention)	t of which is hereby : he entire and exclus	acknowledged, th ive right, title and	e undersigned ASSIGNOR hereby sells, interest to the invention entitled
****	LAYOUT METHOD AND MI	ETHOD OF MAN	IUFACTURING	SEMICONDUCTOR
	DEVICE			
relati Unite	ng to International Patent Applica d States was executed on even o	ation PCT/JP/_ date herewith or, if n	_and/or for which ot so executed, v	application for Letters Patent of the vas:
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(b)	filed on	· · · · · · · · · · · · · · · · · · ·	***************************************	
	Serial No			ttorney is hereby authorized to specified data, when known.
contin	o said application and all Letters nuation, division, renewal, substit s for which the said Letters Paten nafter, "said application(s) and Le	ute, reissue or reex it(s) may be granted	amination applica	d on said application and any tion based thereon, for the full term or y extensions thereof (collectively,
ASSI main applic proce acts I	GNEE, to do all acts which the A taining and enforcing protection f cation(s) and the issuance of said eading, and in any litigation or oth	SSIGNEE may deen for said invention, inc of Letters Patent(s), in ter legal proceeding souting all papers, in-	n necessary, des cluding in the pre n any interferenc which may arise cluding separate	paration and prosecution of said e, reissue, reexamination, or public use or be declared in relation to same, such assignments and declarations, taking all
١N	WITNESS WHEREOF, the unde	ersigned inventor(s)	has (have) affixe	d his/her/their signature(s).
1)	TakonuYj Hironoto (Signature)	Takanori H (Type N		<u>Apr. 26, 20/2</u> (Date)
2)		Toshio	HINO	•
	(Signature)	(Туре N	ame)	(Date)
3)		Tsuyoshi	SAKATA	
,0000	(Signature)	(Type N	ame)	(Date)
4)		Yutaka N	/IIZUNO	

1/1

Katsuya OGATA

(Type Name)

(Type Name)

(Signature)

(Signature)

(Date)

(Date)

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

FUJITSU SEMICONDU	CTOR LIMITED		
2-10-23 Shin-Yokohama	a, Kohoku-ku, Yokoh	ama-shi, Kanagav	va 222-0033 Japan
(hereinafter, "ASSIGNEE"), the re assigns and transfers to ASSIGN (Title of Invention) LAYOUT METHOD AND DEVICE	EE the entire and exclus	sive right, title and inte	
relating to International Patent Ap United States was executed on e	oplication PCT/JP/ ven date herewith or, if r	and/or for which app not so executed, was:	olication for Letters Patent of the
(a) executed on	······3	(Insert date of execu concurrent)	ution of application, if not
(b) filed on	······································		ney is hereby authorized to cified data, when known.
terms for which the said Letters F hereinafter, "said application(s) a	Jbstitute, reissue or reex Patent(s) may be granted nd Letters Patent(s)"). en requested by said AS the ASSIGNEE may dee	amination application I and including any exi SIGNEE and without on m necessary, desirable	based thereon, for the full term or tensions thereof (collectively, charge to but at the expense of said te or expedient, for securing,
application(s) and the issuance o proceeding, and in any litigation of	f said Letters Patent(s), i or other legal proceeding o executing all papers, in	in any interference, re which may arise or be cluding separate assig	issue, reexamination, or public use a declared in relation to same, such gnments and declarations, taking at
IN WITNESS WHEREOF, the	undersigned inventor(s) Takanori H		s/her/their signature(s).
1) (Signature)	(Type N		(Date)
m Andre 11	. •	•	3
4) <u>178400 (Lyste</u> (Signature)	(Type N	HINO lame)	Apr. 26, 2012 (Date)
3)	Tsuyoshi		Aronagy.
(Signature)	(Type N		(Date)
4)	Yutaka N	•	, ,
(Signature)	(Type N		(Date)
5)	Katsuya	OGATA	
(Signature)	(Type N		(Date)

1/1

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

اند مد بدر	FUJITSU SEMICONDUCTO 2-10-23 Shin-Yokohama, Ko		ama-shi, Kanag	awa 222-0033 Japan
assi	einafter, "ASSIGNEE"), the receipt gns and transfers to ASSIGNEE to e of Invention)	t of which is hereby ne entire and exclus	acknowledged, the sive right, title and it	undersigned ASSIGNOR hereby sells, nterest to the invention entitled
	LAYOUT METHOD AND MI DEVICE	ETHOD OF MAN	NUFACTURING	SEMICONDUCTOR
relat Unit	ting to International Patent Applica ed States was executed on even o	ition PCT/JP/_ date herewith or, if r	and/or for which a not so executed, wa	application for Letters Patent of the is:
(a)	executed on	,	(Insert date of ex concurrent)	ecution of application, if not
(d)	filed on			orney is hereby authorized to pecified data, when known.
here T ASS mair appl proc acts	IGNEE, to do all acts which the Antaining and enforcing protection foliation(s) and the issuance of said reeding, and in any litigation or oth	etters Patent(s)"). quested by said AS SSIGNEE may dee or said invention, in I Letters Patent(s), er legal proceeding cuting all papers, in	SIGNEE and withor m necessary, desir cluding in the preprint in any interference, which may arise or cluding separate as	ut charge to but at the expense of said able or expedient, for securing, aration and prosecution of said reissue, reexamination, or public use to be declared in relation to same, such ssignments and declarations, taking all
13	N WITNESS WHEREOF, the unde	ersigned inventor(s)	has (have) affixed	his/her/their signature(s).
1) _		***************************************	RAMOTO	
	(Signature)	(Туре Л	lame)	(Date)
2}			HINO	
	(Signature)	(Type N	lame)	(Date)
3) _	Gundi Likite	***************************************	SAKATA	Apr. 26, 2012
	(Signature)	(Type N	lame)	(Date)
4)		Yutaka I	222222222222222222222222222222222222222	
	(Signature)	(Type N	lame)	(Date)
5)		Katsuya	OGATA	
	(Signature)	(Туре Л	lame)	(Dete)

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IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

	JJITSU SEMICONDUCTOF 10-23 Shin-Yokohama, Koh	R LIMITED noku-ku, Yokohama-shi, Kani	agawa 222-0033 Japan
assigns (Title of	and transfers to ASSIGNEE the Invention) YOUT METHOD AND ME	of which is hereby acknowledged, to entire and exclusive right, title and THOD OF MANUFACTURIN	
DE	EVICE		
relating United	to International Patent Application	on PCT/JP/and/or for whic ite herewith or, if not so executed,	h application for Letters Patent of the was:
(a) 8:	xecuted on	(Insert date of concurrent)	execution of application, if not
	ed on	Assignee's	attorney is hereby authorized to specified data, when known.
ASSIGI maintain applicat proceed acts to i rightful	NEE, to do all acts which the AS- ning and enforcing protection for tion(s) and the issuance of said t ting, and in any litigation or other notude but not be limited to exec- paths, providing sworn testimon	SIGNEE may deem necessary, de said invention, including in the pre- Letters Patent(s), in any interferent r legal proceeding which may arise uting all papers, including separate y, and obtaining and producing evi	eparation and prosecution of said be, reissue, reexamination, or public use or be declared in relation to same, such assignments and declarations, taking all dence.
	A INESS WHEREUT, the under	signed inventor(s) has (have) affixi	ed nis/ner/their signature(s).
1)	***************************************	Takanori HIRAMOTO	
	(Signature)	(Type Name)	(Date)
2)	······································	Toshio HINO	
	(Signature)	(Type Name)	(Date)
3)	er.	Tsuyoshi SAKATA	
	(Signature)	(Type Name)	(Date)
4)	Gitala Mizual	Yutaka MIZUNO	ADV. SA. ZOLZ.
Ü	(Signature)/	(Type Name)	T (bale)
5)		Katsuya OGATA	
	(Signature)	(Type Name)	(Date)

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IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

	FUJITSU SEMICONDUCTO	OR LIMITED		
o S	2-10-23 Shin-Yokohama, K	ohoku-ku, Yokoh	iama-shi, Kanaga	wa 222-0033 Japan
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ass	reinafter, "ASSIGNEE"), the receip igns and transfers to ASSIGNEE (le of Invention)	ot of which is hereby the entire and exclus	acknowledged, the u sive right, title and int	ndersigned ASSIGNOR hereby sells erest to the invention entitled
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(3)	executed on	***************************************	(Insert date of exec	cution of application, if not
(b)	Serial No/_			mey is hereby authorized to cified data, when known.
ASS mai app proc acts righ	SIGNEE, to do all acts which the Antaining and enforcing protection lication(s) and the issuance of saideding, and in any litigation or other.	ASSIGNEE may dee for said invention, in d Letters Patent(s), ner legal proceeding ecuting all papers, in ony, and obtaining a	m necessary, desirat cluding in the prepar- in any interference, n which may arise or t cluding separate ass nd producing evidence	ation and prosecution of said eissue, reexamination, or public use be declared in relation to same, such ignments and declarations, taking al ce.
1)		Takanori H	, .	• • • • • • • • • • • • • • • • • • • •
	(Signature)	(Type ∧	lame)	(Date)
2)	₽	Toshio	HINO	
~	(Signature)	(Type N	lame)	(Date)
3)		Tauyoshi	SAKATA	
.**	(Signature)	(Type N	lame)	(Date)
4)		Yutaka I	VIZUNO	
	(Signature)	(Type N	lame)	(Date)
5) _	ROLLING OGATA	Katsuya	OGATA	Apr. 26, 2012
.**	(Signature)	(Type N	lame)	(Date)

PATENT REEL: 028368 FRAME: 0961

RECORDED: 06/13/2012